

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Om P. Agrawal; Bai Nguyen; Kuang Chi; Brad

Sharpe-Geisler; Giap Tran

Assignee: Lattice Semiconductor Corporation

Title: Scalable Serializer-Deserializer Architecture

And Programmable Interface

Serial No.: 10/619,645 Filing Date: 07/14/2003

Examiner: Jason Crawford Group Art 2819

Unit:

M-15135 US Confirmation 9559

Docket No.: M-15135 US Conf

Irvine, California March 20, 2006

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

37 C.F.R. 1.131 DECLARATION

Dear Sir:

We, Om P. Agrawal, Bai Nguyen, Kuang Chi, Brad Sharpe-Geisler, and Giap Tran, declare as follows:

> 1. We were or are currently employed at Lattice Semiconductor Corporation and are the inventors for the above-referenced patent application entitled "Scalable Serializer-Deserializer Architecture and Programmable Interface" (hereinafter referred to as "the Patent Application").

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- 2. Within the United States, we conceived and reduced to practice the invention disclosed in the Patent Application prior to April 28, 2003, the effective date of U.S. Patent No. 6,894,530.
- 3. The reduction to practice (referred to in paragraph 2) resulted from the implementation of the invention (e.g., the invention as disclosed in the Patent Application and recited in Claims 1-20 of the Patent Application) within an ispXPGA product offered by Lattice Semiconductor Corporation.
- 4. The ispXPGA product was first publicly announced by
 Lattice Semiconductor Corporation in a press release
 on July 15, 2002, a copy of which is attached as
 Exhibit A.
- 5. Samples of the ispXPGA product were first released to customers in March 2003 and details of the released product were disclosed in a published Preliminary Data Sheet entitled "ispXPGA Family" dated March 2003 by Lattice Semiconductor Corporation (referred to in the Patent Application on page 15, lines 15-20 and herein referred to as "the Preliminary Data Sheet," a copy of which is attached as Exhibit B).

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- 6. The Preliminary Data Sheet shows a successful exemplary implementation of the invention in the ispXPGA product prior to April 28, 2003.
- 7. Alternatively to paragraphs 2 through 6, a patent application draft (hereinafter referred to as "the Patent Application Draft") corresponding to the Patent Application was completed prior to April 28, 2003 (a copy of the letter dated April 7, 2003 enclosing the Patent Application Draft to one of the inventors is attached as Exhibit C).
- 8. The Patent Application Draft was reviewed by the inventors and approved for filing by Lattice Semiconductor Corporation, with due diligence during the time from the completion of the Patent Application Draft prior to April 28, 2003 to the filing of the Patent Application on July 14, 2003.

I declare that all statements made herein of my own knowledge are true, all statements made herein on information and belief are believed to be true, and all statements made herein are made with the knowledge that whoever, in any matter within the jurisdiction of the Patent and Trademark Office, knowingly and willfully falsifies, conceals, or covers up by any trick, scheme, or device a material fact, or makes any false, fictitious or fraudulent statements or representations,

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or makes or uses any false writing or document knowing the same to contain any false, fictitious or fraudulent statement or entry, shall be subject to the penalties including fine or imprisonment or both as set forth under 18 U.S.C. 1001, and that violations of this paragraph may jeopardize the validity of the application or this document, or the validity or enforceability of any patent, trademark registration, or certificate resulting therefrom.

Full name of first joint inventor:	Om P. Agrawal		
Inventor's Signature:		Date:	
Full name of second joint inventor:	Bai Nguyen		
Inventor's Signature:		Date:	7/16/06
Full name of third joint inventor:	Kuang Chi		
Inventor's Signature: Kua	e-Kan Chi	Date:	3/16/04
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Full name of fourth joint inventor:	Brad Sharps-Gejeter		· · · · · · · · · · · · · · · · · · ·
Inventor's Signature:	and Time	Date:	3/6/05
	3.1		
Full name of fourth joint inventor:	Giap Tran		
Inventor's Signature:	and -	Date:	3 16 6,5
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Full name of 1 joint inventor:	Om P. Agrawal	On	P. Ag	rand
Inventor's Signature:			Date:	3/20/06
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Pull name of second joint inventor:	Bai Nguyen			
Inventor's Signature:			Date:	<u> </u>
Full name of third joint inventor:	Kuang Chi			
Inventor's Signature:			Date:	T
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Full name of fourth joint inventor: Inventor's Signature:	Brad Sharpe-Geisler			r —— -
interior a Signature.			Date:	<u> </u>
Full name of fourth joint inventor: Inventor's Signature:	Giap Tran		Date:	
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